



Silicon Carbide Dual Schottky Power Rectifier 10A, 1200V

ORDERABLE PART NUMBERS			
	MSiCSN10120CC	MSiCSN10120CA	MSiCSN10120D
Configuration	Common Cathode	Common Anode	Doubler

DESCRIPTION

These dual 1200 V rated SiC Schottky rectifiers are in a hermetically sealed package with options for common cathode, common anode, and doubler configurations. They offer very fast switching capabilities with greater efficiency at higher operating temperatures compared to existing ultrafast silicon rectifiers.

Important: For the latest information, visit our website <http://www.microsemi.com>.

FEATURES

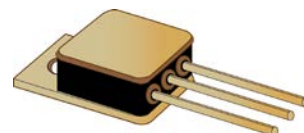
- TO-257 package
- Lightweight
- Hermetically sealed package
- Internal metallurgical bonds
- High temperature (T_J) +175 °C
- Zero reverse recovery current
- Temperature independent switching behavior
- Very fast switching compared to fast or ultrafast rectifiers
- Positive V_F temperature coefficient (parallel devices for higher currents)
- RoHS compliant versions are available

APPLICATIONS / BENEFITS

- Schottky barrier diode for military, space and other high reliability applications
- Switching power supplies or other applications requiring extremely fast switching and essentially no switching losses
- High forward surge capability
- High reverse voltage capability with very fast switching
- Inherently radiation hard >100 krad as described in Microsemi [MicroNote 050](#)

MAXIMUM RATINGS @ $T_C = +25\text{ °C}$ unless otherwise noted

Parameters/Test Conditions	Symbol	Value	Unit
Junction and Storage Temperature	T_J and T_{STG}	-65 to +175	°C
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.6	°C/W
Working Peak Reverse Voltage	V_{RWM}	1200	V
Non-Repetitive Peak Inverse Voltage	V_{RSM}	1200	V
DC Blocking Voltage	V_{DC}	1200	V
Average DC Output Current @ 25 °C	I_O	10	A
Non-Repetitive Sinusoidal Surge Current @ $t_p = 8.3\text{ ms}$, half sinewave, $I_O = 0$; $V_{RM} = 0$	I_{FSM}	50	A



TO-257 Package

Also available in:

Dual U3 package
(surface mount)

 [MSiCSS10120CC](#)

U3 package
(surface mount)

 [MSiCSS10120](#)

TO-257 package
(leaded)

 [MSiCSN10120](#)

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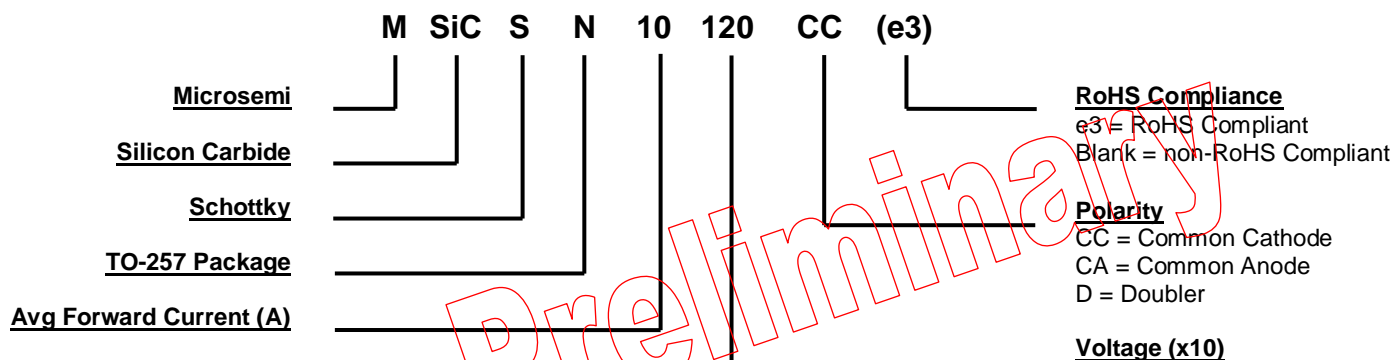
Website:

www.microsemi.com

MECHANICAL and PACKAGING

- CASE: Nickel plated copper base & 1020 steel frame
- TERMINALS: Solder dipped copper cored 52 alloy or RoHS compliant matte/tin plating
- MARKING: Alpha numeric
- POLARITY: See [schematic](#) on last page
- WEIGHT: Approximately 3.43 grams
- See [package dimensions](#) on last page.

PART NOMENCLATURE



SYMBOLS & DEFINITIONS

Symbol	Definition
C_J	Junction Capacitance: The junction capacitance in pF at a specified frequency (typically 1 MHz) and specified voltage.
I_F	Forward Current: The forward current dc value, no alternating component.
I_R	Reverse Current: The maximum reverse (leakage) current that will flow at the specified voltage and temperature.
T_J	Junction Temperature: The temperature of a semiconductor junction.
V_F	Forward Voltage: The forward voltage the device will exhibit at a specified current (typically shown as maximum value).
V_R	Reverse Voltage: The reverse voltage dc value, no alternating component.

ELECTRICAL CHARACTERISTICS @ $T_A = +25^\circ\text{C}$ unless otherwise noted

Parameters / Test Conditions	Symbol	Min.	Max.	Typ.	Unit
Forward Voltage* $I_F = 1\text{ A}$, $T_J = 25^\circ\text{C}$ $I_F = 2.5\text{ A}$, $T_J = 25^\circ\text{C}$ $I_F = 5.0\text{ A}$, $T_J = 25^\circ\text{C}$ $I_F = 10.0\text{ A}$, $T_J = 25^\circ\text{C}$	V_F		1.1 1.2 1.4 1.8		V
Reverse Current $V_R = 1200\text{ V}$, $T_J = 25^\circ\text{C}$ $V_R = 1200\text{ V}$, $T_J = 175^\circ\text{C}$	I_R		100 200		μA
Junction Capacitance $V_R = 0\text{ V}$ $f = 1\text{ MHz}$	C_J			1200	pF

* Pulse test: Pulse width 300 μsec , duty cycle 2%.

Preliminary

Technical drawing of a 3-pin connector showing front and side views with dimensions and labels.

Front View Dimensions and Labels:

- MHO:** Overall height of the connector body.
- LL:** Height of the lower section (terminals).
- TERMS 1 2 3:** Labels for the three terminals.
- LD 3 plcs:** Label for the three terminals.
- LS:** Label for the terminal spacing.
- TL:** Height of the upper section (housing).
- TW:** Width of the upper section.
- MHD -Y-:** Label for the mounting hole diameter.

Side View Dimensions and Labels:

- CH:** Height of the upper section.
- BL:** Height of the lower section.
- LO:** Label for the lower section.
- T-:** Label for the terminal width.
- TT:** Label for the terminal thickness.

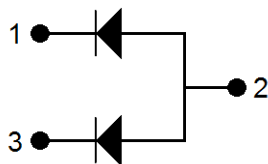
Bottom View:

⊕ ∅ 0.014 (M) T Y (L)

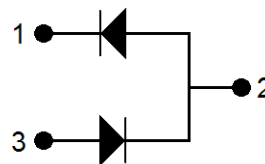
Ltr	Dimensions			
	Inch		Millimeters	
	Min	Max	Min	Max
BL	0.410	0.430	10.41	10.92
CH	0.190	0.200	4.83	5.08
LD	0.025	0.035	0.64	0.89
LL	0.505	0.595	12.82	15.11
LO	0.120 BSC		3.05 BSC	
LS	0.100 BSC		2.54 BSC	
MHD	0.140	0.150	3.56	3.81
MHO	0.527	0.537	13.39	13.64
TL	0.645	0.665	16.38	16.89
TT	0.035	0.045	0.89	1.14
TW	0.410	0.420	10.41	10.67
TERM 1	SEE SCHEMATIC			
TERM 2	SEE SCHEMATIC			
TERM 3	SEE SCHEMATIC			

1. Dimensions are in inches.
2. Millimeters equivalents are given for general information only.
3. Glass meniscus included in dimension TL and BL.

TERM 1 = ANODE
TERM 2 = CATHODE
TERM 3 = ANODE



TERM 1 = CATHODE
TERM 2 = ANODE
TERM 3 = CATHODE



TERM 1 = CATHODE
TERM 2 = CENTER TAP
TERM 3 = ANODE